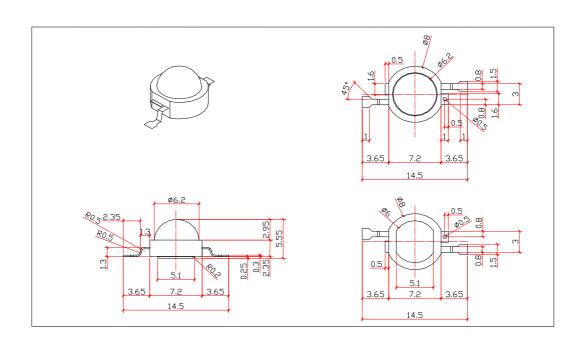


### 5W HIGH POWER LED (EMITTER V) B081E-5W

D001L-344				
Features	Applications			
* Long operating life	* Reading lights (car, bus, aircraft)			
* Highest flux	* LCD Backlights/light Guides			
* Available in White:2500K-25000K	* Fiber optic alternative/ Decorative Entertainment			
* Lambertian radiation pattern	* Mini-accent/Up lighters/Down lighters/ Orientation			
* More energy efficient than incandescent and most	* Indoor/Outdoor commercial and Residential			
halogen lamps	Architectural			
* Low voltage DC operated	* Cove/Under shelf/Task			
* Cool beam, safe to the touch	* Bollards/Security/Garden			
* Instant light (less than 100ns )	* Portable (flashlight, bicycle)			
* Fully dimmable	* Edge-lit signs (Exit, point of sale)			
* No UV	* Automotive Exit (Stop-Tail-Turn,CHMSL, Mirror			
	Side Repeat)			
* Superior ESD protection	* Traffic signaling / Beacons / RailCrossing and			
	Wayside			
* Eutectic die bonding				
* RoHS compliant				

### **PACKAGE**





Typical Optical/ Electrical Characteristics @TJ=25

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=700mA	6		8	V
Reverse Current	IR	VR=5v			50	uA
50% Power Angle	201/2	IF=700mA		120		deg
Luminous Intensity	φV	IF=700mA	60		80	lm
Recommend Forward Current	IF			700		mA
Wavelength	d	IF=700mA		470		nm
Thermal Resistance, Junction to Case	RJP	IF=700mA		10		/w

#### Notes:

- 1. Tolerance of measurement of forward voltage±0.1V.
- 2. Tolerance of measurement of peak Wavelength±2.0nm.
- 3. Tolerance of measurement of luminous intensity±15%.

**Absolute Maximum Rating** 

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	lF	700	mA
Peak Forward Current*	<b>I</b> FP	1200	mA
Reverse Voltage	VR	5	V
Power Dissipation	PD	5000	mW
Electrostatic discharge	Esp	±4500	V
Operation Temperature	Topr	-40~+80	
Storage Temperature	Тѕтс	-40~+100	
Lead Soldering Temperature*	TsoL	Max. 260 for 3sec Max.	

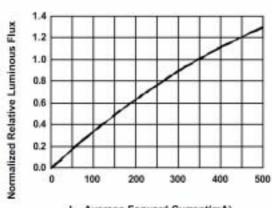
<sup>\*</sup>IFP Conditions : Pulse Width≤10msec duty≤1/10

- \* All high power emitter LED products mounted on aluminum metal-core printed circuit board, can be lighted directly, but we do not recommend lighting the high power products for more than 5 seconds without a appropriate heat dissipation equipment.
- \* Re-flow, wave peak and soak- stannum soldering etc.is not suitable for this products.
- \* Suggest to solder it by professional high power LED soldering machine.
- \* Can use invariable-temperature searing-iron with soldering condition:≤260 degree less than 3 seconds.



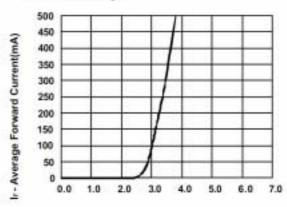
### (TJ=25 Unless Otherwise Noted)

Fig 1. Relative Luminous FLux vs. Forward Current



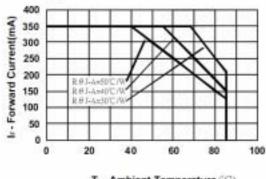
Is - Average Forward Current(mA)

Fig 2. Forward Current vs. Forward Voltage



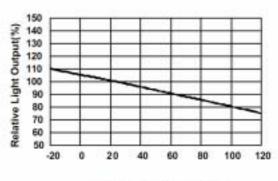
Vr - Forward Voltage(Volts)

Fig 3. Maximum Forward Current vs. Ambient Temperature. Derating based on Taxas =120°C



Ta - Ambient Temperature (°C)

Fig 4. Relative Light Output vs. Junction Temperature



Junction Temperature, T<sub>i</sub>(C)

Fig 5. Relative Spectral Power Distribution vs. Wavelength

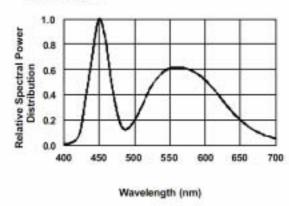
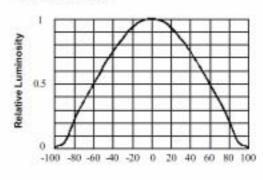
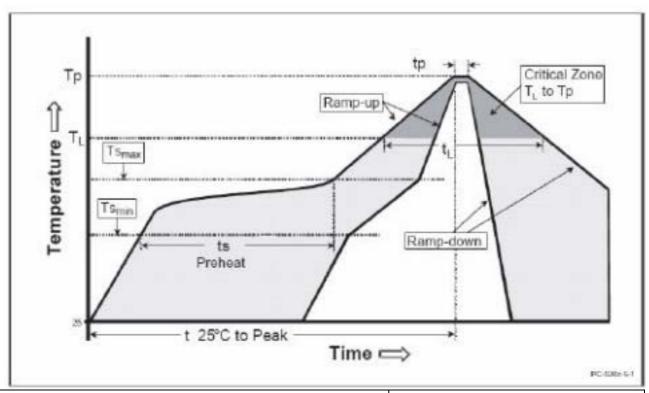


Fig 6. Relative Luminosity vs. Radiation Angle



Radiation Angle(Degrees)





Profile Feature	Pb-Free Assembly
Preheat	
- Temperature Min (Tsmin)	60-180 seconds
- Temperature Max (Tsmax)	150 °C
- Time (tsmin to tsmax)	200 °C
- Temperature (TL)	
- Time (tL)	60-150 seconds
Time maintained above:	217 °C
Peak/Classification Temperature (Tp)	260 °C
Time within 5 °C of actual Peak Temperature (tp)	20-40 seconds
Ramp-Down Rate	6 °C/second max.
Time 25 °C to Peak Temperature	8 minutes max.

#### **Notes**

### 1. All temperatures refer to Solder Pad